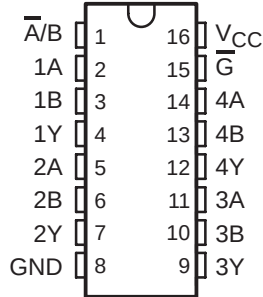


SN54HC158, SN74HC158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

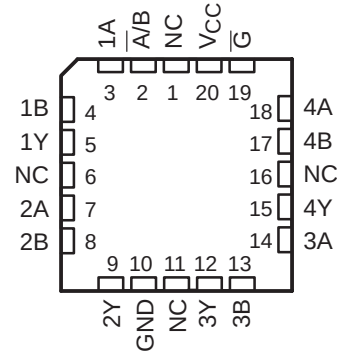
SCLS296D – JANUARY 1996 – REVISED OCTOBER 2003

- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80- μ A Max I_{CC}
- Typical $t_{pd} = 11$ ns
- ± 6 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max

SN54HC158 . . . J OR W PACKAGE
SN74HC158 . . . D, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54HC158 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

These data selectors/multiplexers contain inverters and drivers that supply full data selection to the four output gates. A separate strobe ($\bar{G}$) input is provided. A 4-bit word is selected from one of two sources and is routed to the four outputs. The 'HC158 devices' outputs provide inverted data.

ORDERING INFORMATION

T _A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube of 25	SN74HC158N	SN74HC158N
	SOIC – D	Tube of 40	SN74HC158D	HC158
		Reel of 2500	SN74HC158DR	
		Reel of 250	SN74HC158DT	
	SOP – NS	Reel of 2000	SN74HC158NSR	HC158
	TSSOP – PW	Tube of 90	SN74HC158PW	HC158
		Reel of 2000	SN74HC158PWR	
Reel of 250		SN74HC158PWT		
–55°C to 125°C	CDIP – J	Tube of 25	SNJ54HC158J	SNJ54HC158J
	CFP – W	Tube of 150	SNJ54HC158W	SNJ54HC158W
	LCCC – FK	Tube of 55	SNJ54HC158FK	SNJ54HC158FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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UNLESS OTHERWISE NOTED this document contains PRODUCTION DATA information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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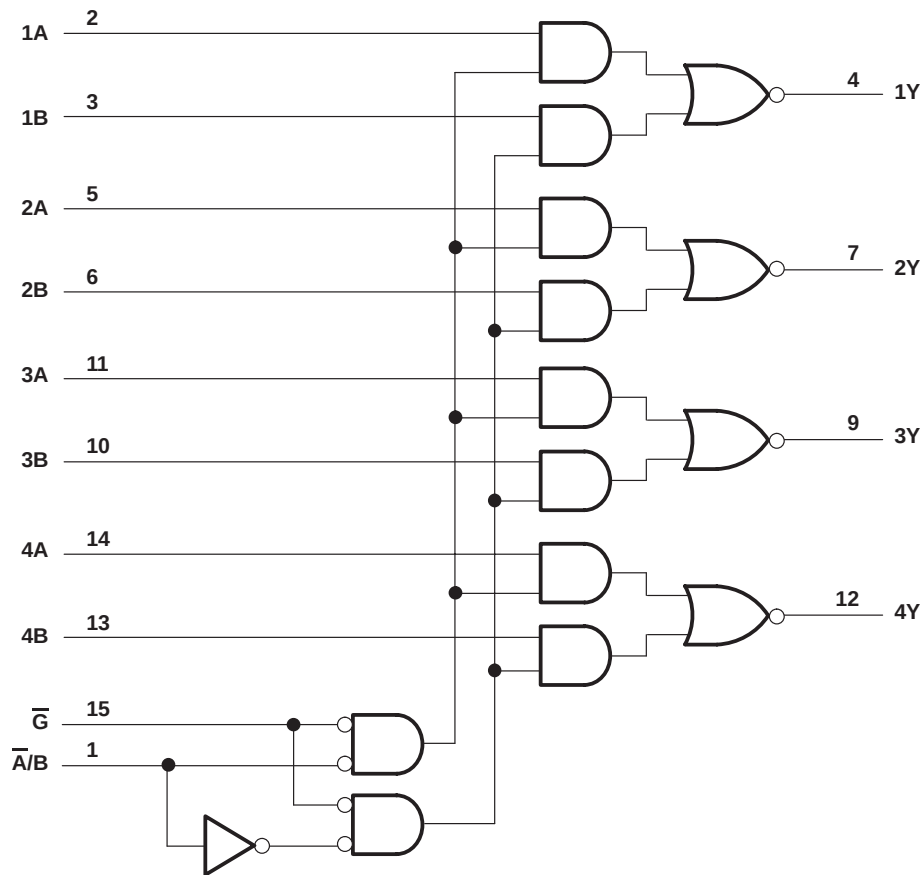
SN54HC158, SN74HC158

QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

SCLS296D – JANUARY 1996 – REVISED OCTOBER 2003

FUNCTION TABLE				
INPUTS				OUTPUT Y
$\overline{G}$	SELECT $\overline{A/B}$	DATA		
		A	B	
H	X	X	X	H
L	L	L	X	H
L	L	H	X	L
L	H	X	L	H
L	H	X	H	L

logic diagram (positive logic)



Pin numbers shown are for the D, J, N, NS, PW, and W packages.

SN54HC158, SN74HC158

QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

SCLS296D – JANUARY 1996 – REVISED OCTOBER 2003

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±35 mA
Continuous current through V_{CC} or GND	±70 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	73°C/W
N package	67°C/W
NS package	64°C/W
PW package	108°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN54HC158			SN74HC158			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		2	5	6	2	5	6	V
V_{IH}	High-level input voltage	$V_{CC} = 2$ V	1.5			1.5			V
		$V_{CC} = 4.5$ V	3.15			3.15			
		$V_{CC} = 6$ V	4.2			4.2			
V_{IL}	Low-level input voltage	$V_{CC} = 2$ V			0.5			0.5	V
		$V_{CC} = 4.5$ V			1.35			1.35	
		$V_{CC} = 6$ V			1.8			1.8	
V_I	Input voltage		0		V_{CC}	0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	0		V_{CC}	V
$\Delta t/\Delta v$	Input transition rise/fall time	$V_{CC} = 2$ V			1000			1000	ns
		$V_{CC} = 4.5$ V			500			500	
		$V_{CC} = 6$ V			400			400	
T_A	Operating free-air temperature		–55		125	–40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54HC158, SN74HC158

QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V _{CC}	T _A = 25°C			SN54HC158		SN74HC158		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = -20 µA	2 V	1.9	1.998		1.9		1.9		V
			4.5 V	4.4	4.499		4.4		4.4		
			6 V	5.9	5.999		5.9		5.9		
		I _{OH} = -6 mA	4.5 V	3.98	4.3		3.7		3.84		
		I _{OH} = -7.8 mA	6 V	5.48	5.8		5.2		5.34		
V _{OL}	V _I = V _{IH} or V _{IL}	I _{OL} = 20 µA	2 V		0.002	0.1		0.1		0.1	V
			4.5 V		0.001	0.1		0.1		0.1	
			6 V		0.001	0.1		0.1		0.1	
		I _{OL} = 6 mA	4.5 V		0.17	0.26		0.4		0.33	
		I _{OL} = 7.8 mA	6 V		0.15	0.26		0.4		0.33	
I _I	V _I = V _{CC} or 0		6 V		±0.1	±100		±1000		±1000	nA
I _{CC}	V _I = V _{CC} or 0, I _O = 0		6 V			8		160		80	µA
C _i			2 V to 6 V		3	10		10		10	pF

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			SN54HC158		SN74HC158		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A or B	Y	2 V		63	125		190		160	ns
			4.5 V		13	25		38		32	
			6 V		11	21		32		27	
	$\overline{A/B}$	Y	2 V		67	125		190		160	
			4.5 V		18	25		38		31	
			6 V		14	21		32		27	
	$\overline{G}$	Y	2 V		59	115		170		145	
			4.5 V		16	23		34		29	
			6 V		13	20		29		25	
t _t		Y	2 V		28	60		90		75	ns
			4.5 V		8	12		18		15	
			6 V		6	10		15		13	

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SN54HC158, SN74HC158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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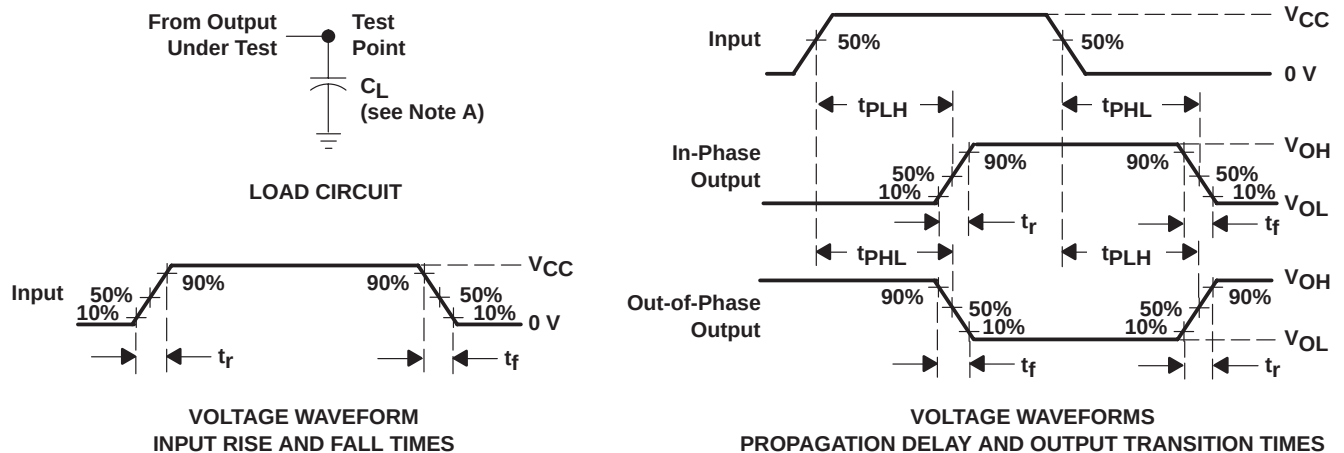
switching characteristics over recommended operating free-air temperature range, $C_L = 150$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC158		SN74HC158		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A or B	Y	2 V		81	190		290		235	ns
			4.5 V		23	38		58		47	
			6 V		18	33		49		41	
	$\bar{A}/B$	Y	2 V		81	210		320		260	
			4.5 V		23	42		64		52	
			6 V		18	36		54		45	
	$\bar{G}$	Y	2 V		91	190		290		235	
			4.5 V		24	38		58		47	
			6 V		18	33		49		41	
t_t		Y	2 V		45	210		315		265	ns
			4.5 V		17	42		63		53	
			6 V		13	36		53		45	

operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load	40	pF

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and test-fixture capacitance.
 - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
 - C. The outputs are measured one at a time with one input transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74HC158D	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	-40 to 85	HC158
SN74HC158DR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC158
SN74HC158DR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC158
SN74HC158DT	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	-40 to 85	HC158
SN74HC158N	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC158N
SN74HC158N.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC158N
SN74HC158NE4	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC158N
SN74HC158NSR	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC158
SN74HC158NSR.A	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC158
SN74HC158PW	Obsolete	Production	TSSOP (PW) 16	-	-	Call TI	Call TI	-40 to 85	HC158
SN74HC158PWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC158
SN74HC158PWR.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC158

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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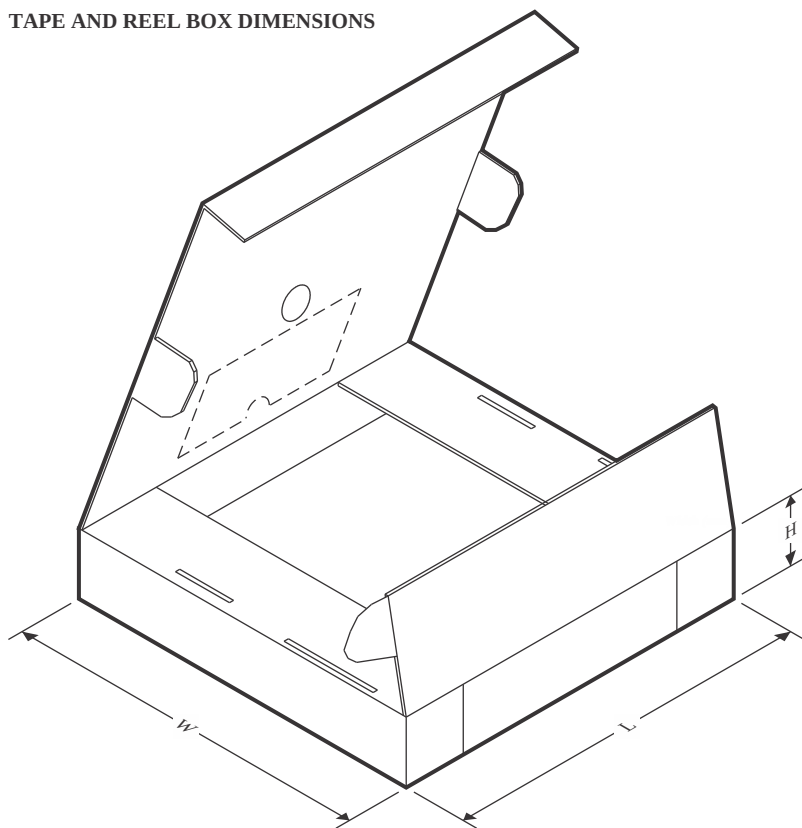
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC158DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC158NSR	SOP	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
SN74HC158PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



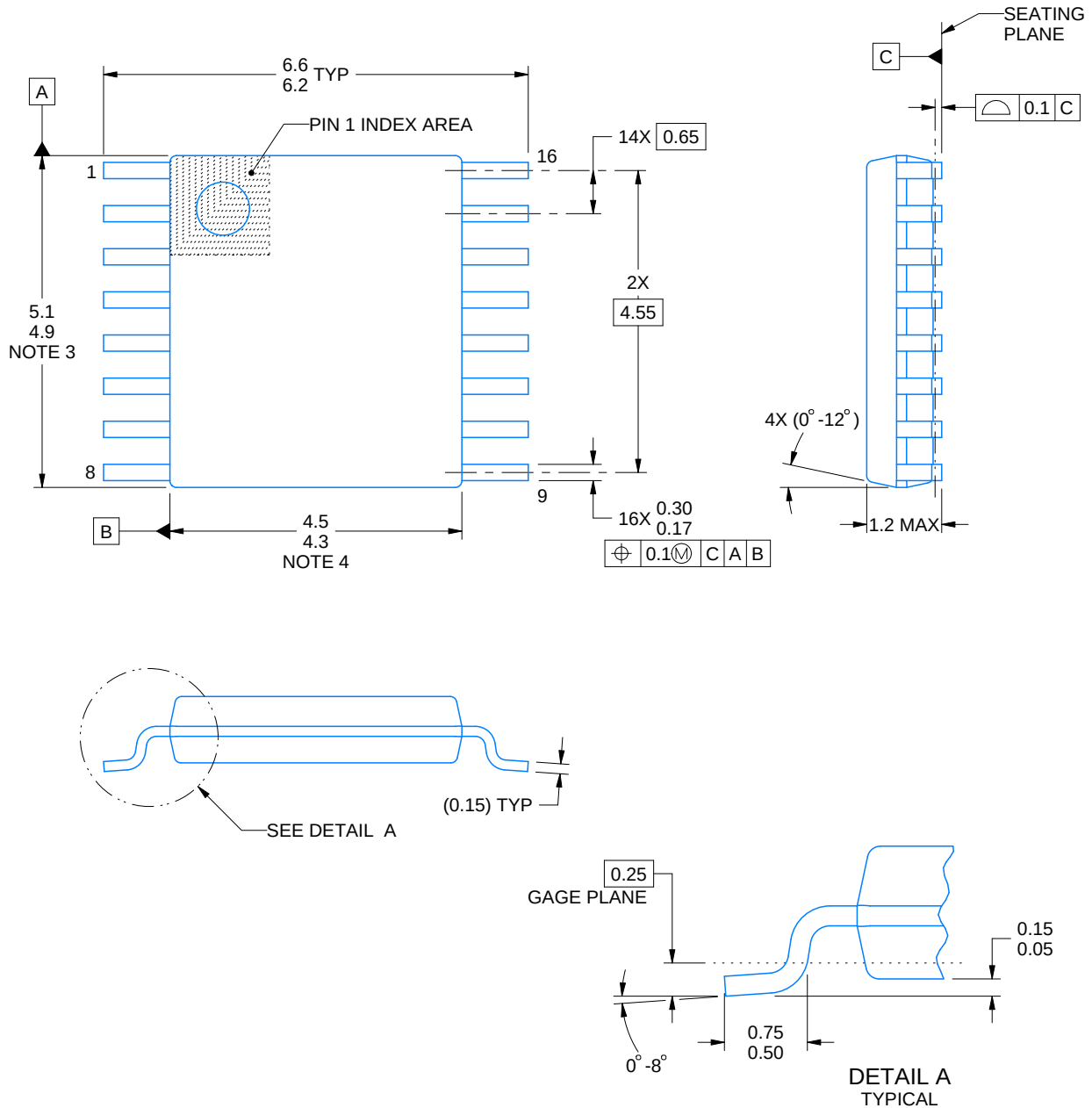
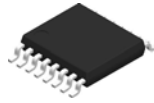
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC158DR	SOIC	D	16	2500	353.0	353.0	32.0
SN74HC158NSR	SOP	NS	16	2000	353.0	353.0	32.0
SN74HC158PWR	TSSOP	PW	16	2000	353.0	353.0	32.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74HC158N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC158N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC158N.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC158N.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC158NE4	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC158NE4	N	PDIP	16	25	506	13.97	11230	4.32



4220204/B 12/2023

NOTES:

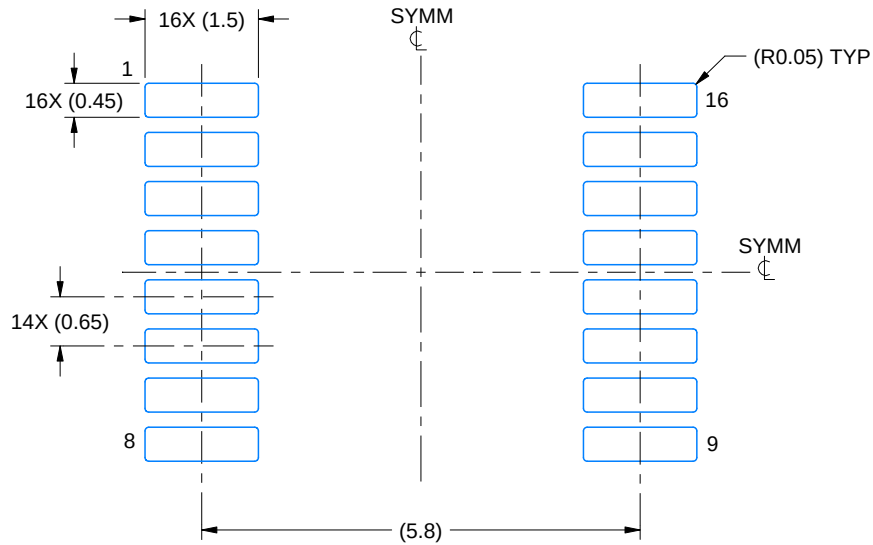
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

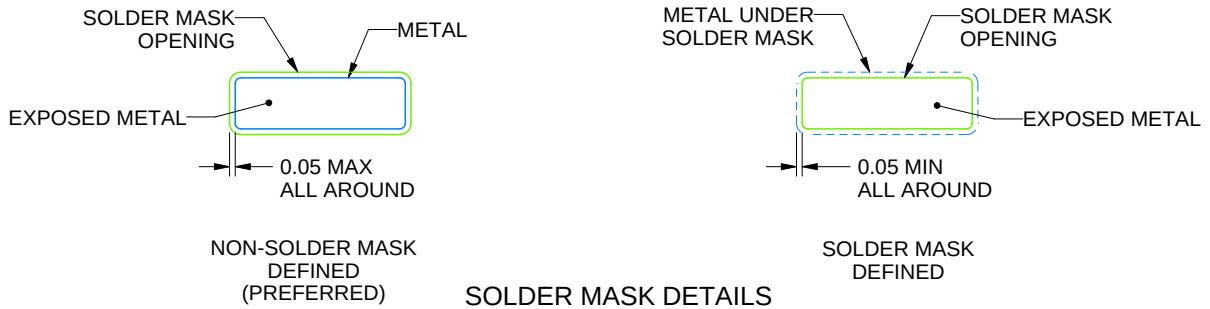
PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220204/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

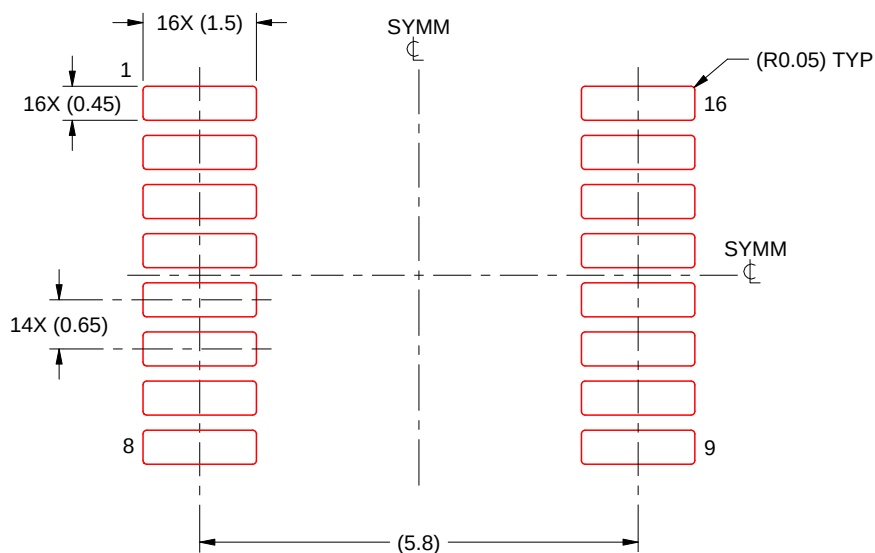
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/B 12/2023

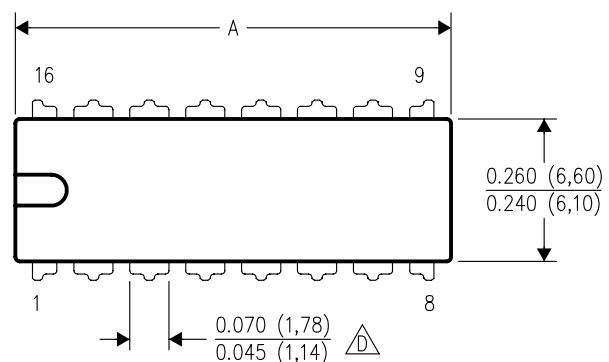
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

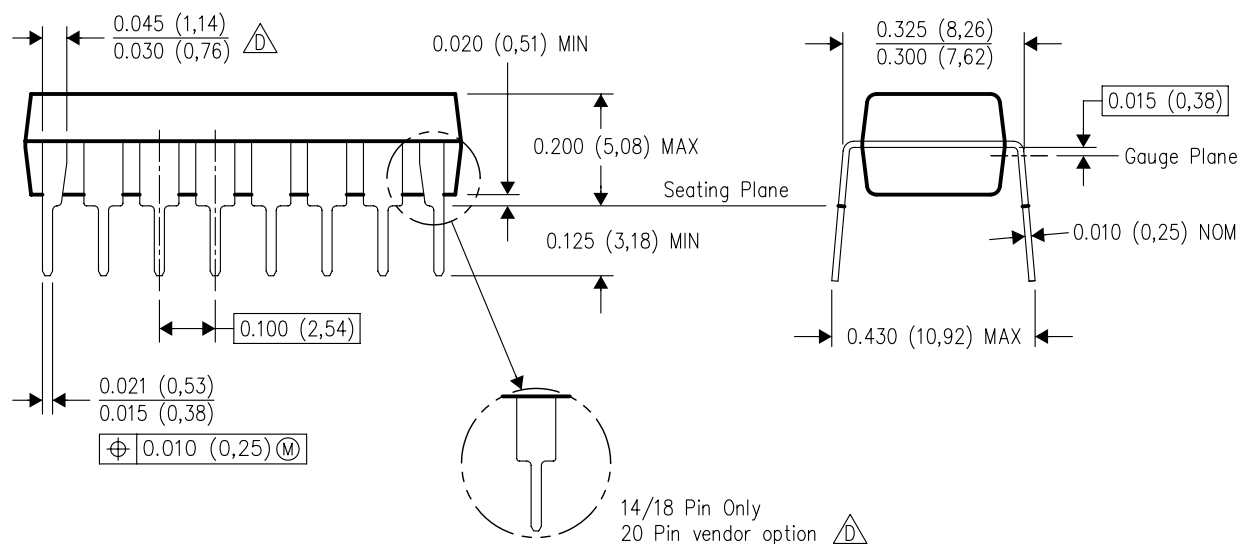
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE

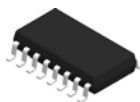


PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

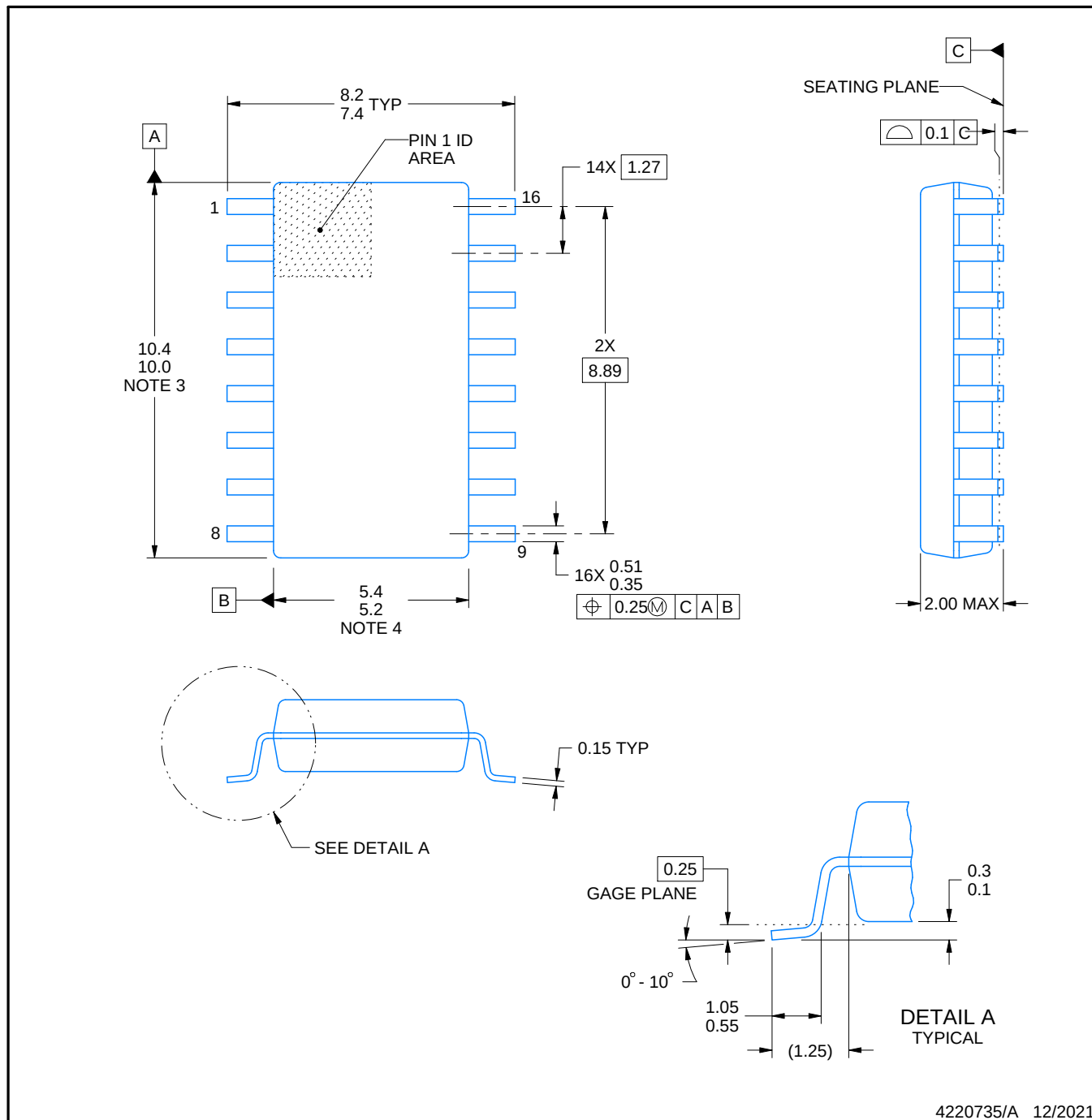


PACKAGE OUTLINE

NS0016A

SOP - 2.00 mm max height

SOP



4220735/A 12/2021

NOTES:

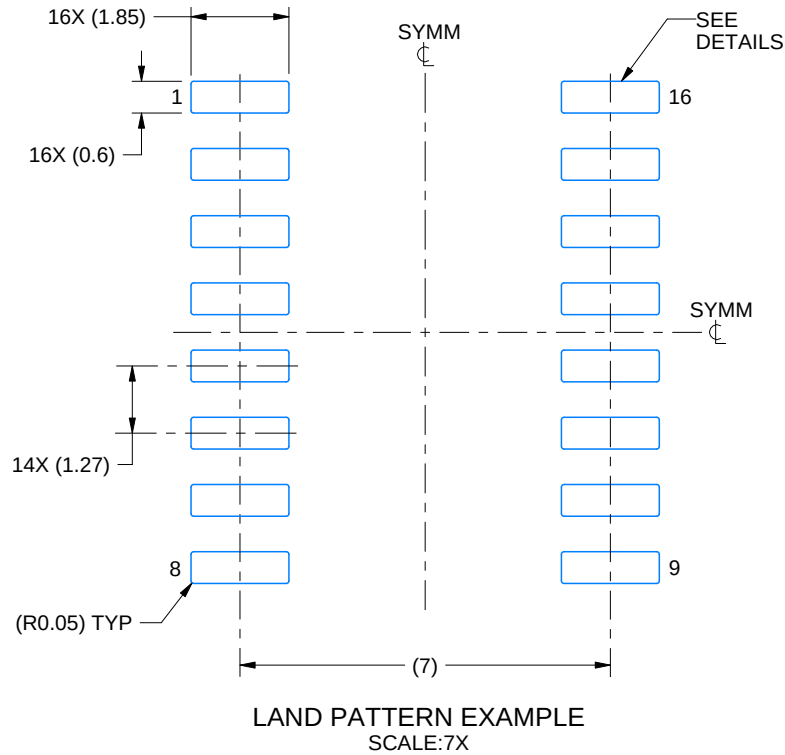
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.

EXAMPLE BOARD LAYOUT

NS0016A

SOP - 2.00 mm max height

SOP

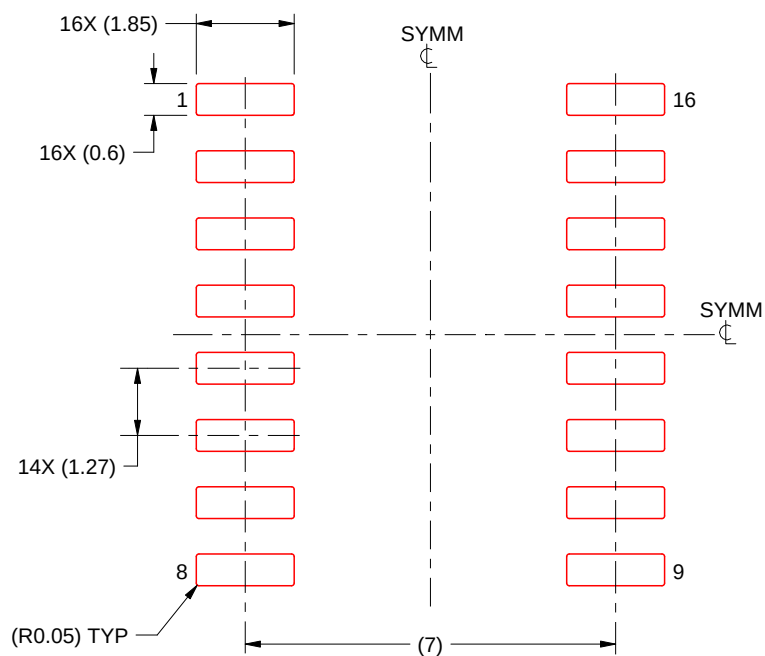


4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL
 SCALE:7X

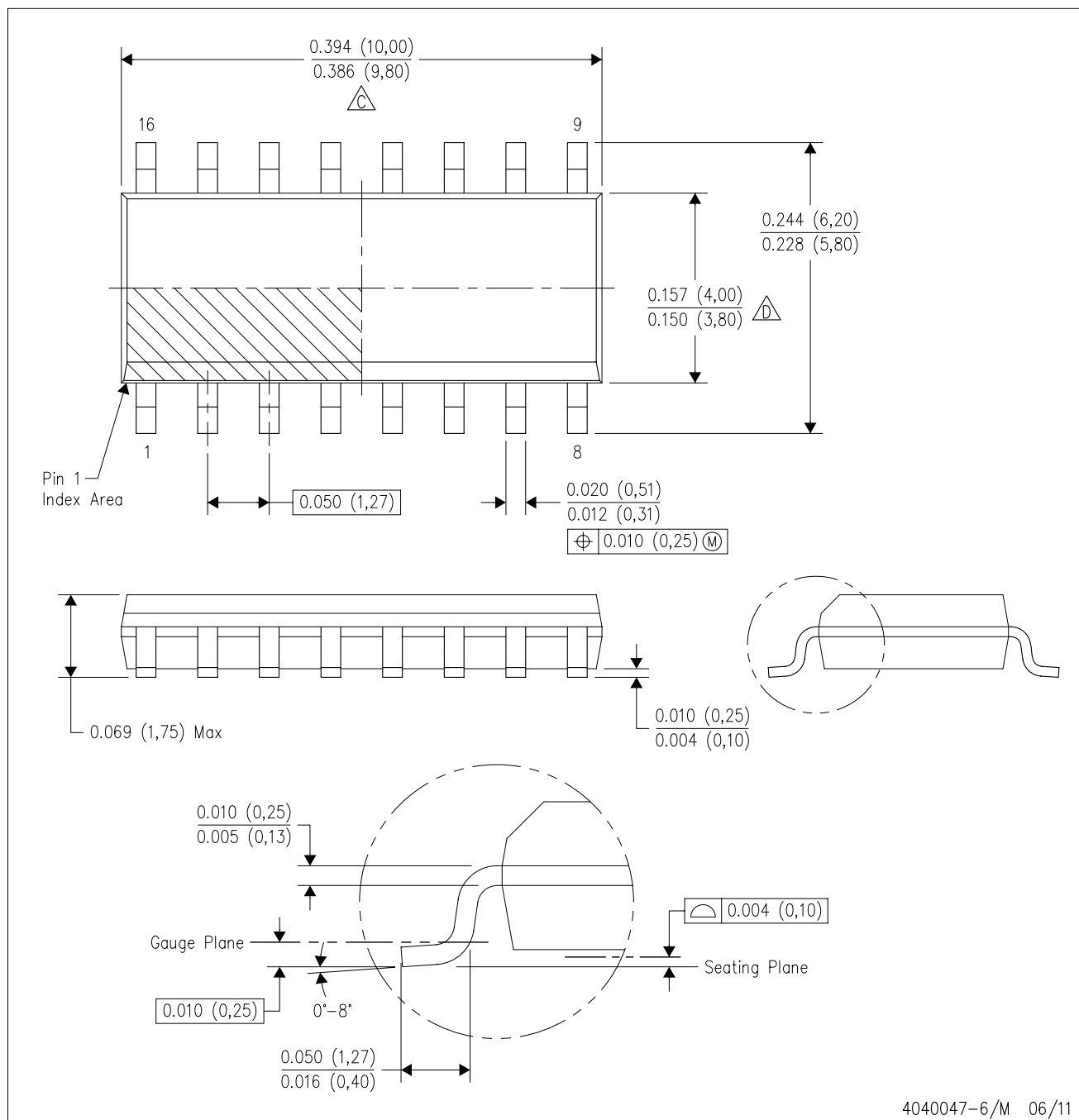
4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 -  D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

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